

an insulative substrate;

a conductor pattern formed on the substrate; and

a protection film coating the substrate and the conductor pattern, wherein the conductor pattern includes a bottom surface entirely contacting the substrate, a top surface opposite to the bottom surface, and a pair of flat side surfaces, each of the side surfaces having a lower side surface covered by the protection film and an upper side surface exposed from the protection film, wherein both the bottom surface and the top surface have widths, both the lower side surface covered by the protection film and the conductor pattern have heights, and wherein the width of the bottom surface is greater than the width of the top surface.

Please cancel claim 3.

8. (Twice Amended) A method for fabricating a printed circuit board comprising the steps of:

etching an insulative substrate including a conductor to form a conductor pattern having a bottom surface entirely contacting the substrate, a top surface opposite to the bottom surface, and a pair of side surfaces, wherein the conductor pattern is formed so that a width of the bottom surface is greater than a width of the top surface;

applying an insulative protection film to the conductor pattern and the substrate; and

removing part of the protection film to expose the top surface and a part of each of the side surfaces.